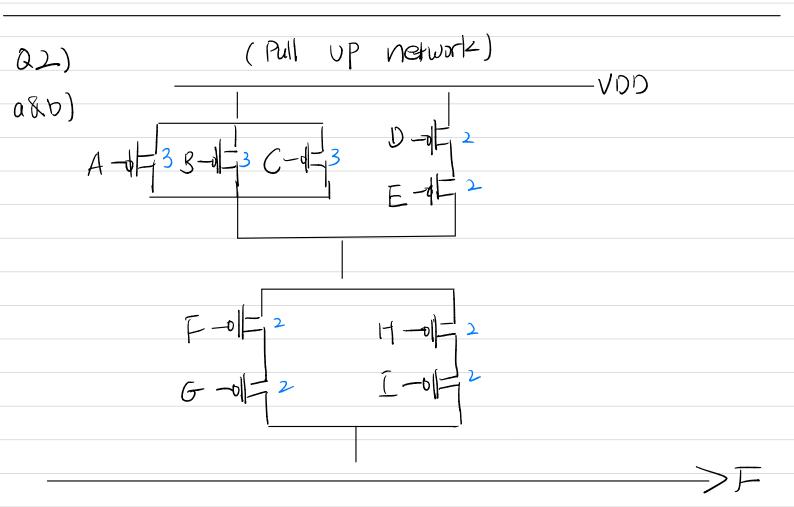
EES03 HW3

- a) Design rules are important during the Physical design phase because they ensure that the designed layout adheres to the manufacturing capability and constrains of the fabrication process
- b) partitioning = creating blocks
 Floor Planning = Placement of blocks
 Placement = Placing Gates on layout
 Racting: wiring.



(Pull down network)

$$F-1 = 4$$

$$C) \qquad \qquad u_n / u_p = \frac{Rn}{Rp} = 2$$

-: worst case 3 transistor in series in plow best case 3 trusister in Parallell in PUN $\frac{3Pn}{Rp/3} = 2$

$$\frac{1}{12}$$
 ratio = $\frac{9 \times 2 : 1}{18 : 1}$

Clock Grid: ensures low local skew by using a wide mesh of wires to minimize RC delays

H-trees = Provide balanced clock sional Paths

W/ minimal skew by using a freetal-like Structure.

Q4)

QS). Contact layer lum 17 Jum [lum. Metal layer 1+2×0.5 2um2um Diffusion layer Zum Zum L=5um 500 ohms = lum x Sum N-well

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Q6).

a) parasitic cap: occurs when 2 parts are separated by a dielectric material, causing unintended capacity coupling

Parasitic resistance occurs from inherent resistance of wires, contacts and diffusion resions due to meterials resistivity.

b) parasitic cap may slow down transistors and increase power comsumption

Porositic resistance may load to wiltuge drop and power dissipation.